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(71) Applicant (for all designated States except US): **EBARA CORPORATION** [JP/JP]; 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **SASAKI, Tatsuya** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho,

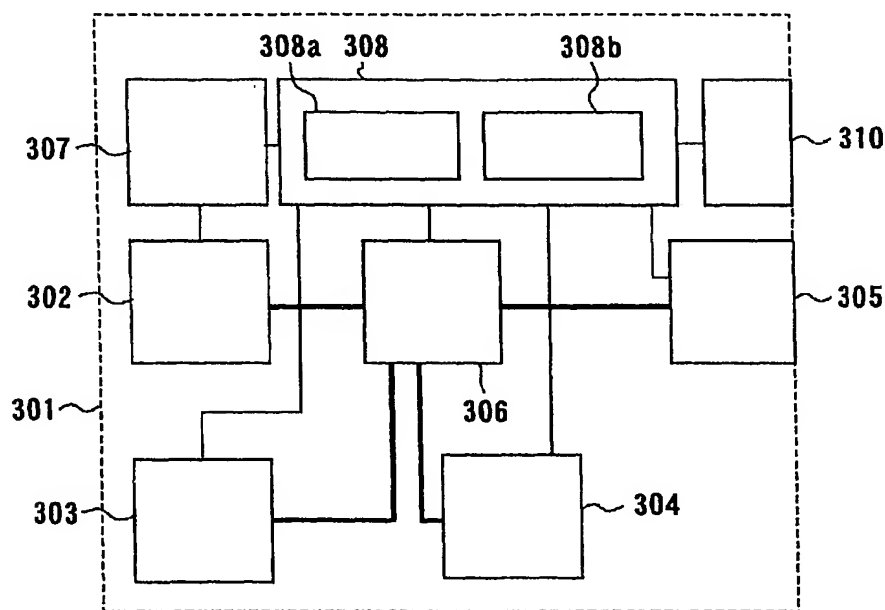
Ohta-ku, Tokyo 1448510 (JP). **YAMADA, Naoshi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **KATSUMATA, Yoshifumi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **SHIMIZU, Noburu** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **TSUNO, Seiryō** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP). **ITSUYA, Takashi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510 (JP).

(74) Agents: **WATANABE, Isamu** et al.; Gowa Nishi-shinjuku 4f, 5-8, Nishi-shinjuku 7-chome, Shinjuku-ku, Tokyo 1600023 (JP).

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(54) Title: POLISHING APPARATUS AND POLISHING METHOD



(57) Abstract: A polishing apparatus has a polishing section (302) configured to polish a substrate and a measurement section (307) configured to measure a thickness of a film formed on the substrate. The polishing apparatus also has an interface (310) configured to input a desired thickness of a film formed on a substrate to be polished and a storage device (308a) configured to store polishing rate data on at least one past substrate therein. The polishing apparatus includes an arithmetic unit (308b) operable to calculate a polishing rate and an optimal polishing time based on the polishing rate data and the desired thickness by using a weighted average method which weights the polishing rate data on a lately polished substrate.

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